SMDRS series, Shielded SMD Power Inductors





◆特征:

- 高饱和电流,低直流电阻
- 闭合磁路设计减少漏磁
- 自动贴装的高精度尺寸
- 多种封装尺寸和宽电感范围
- 符合 RoHS,无卤和 REACH

◆用途:

- 薄型 TV、液晶显示器、AV 设备、游戏设备
- 其他各种电子仪器
- DC/DC 转换器等

◆环境:

工作温度: -40℃ 至+125℃
 (包括线圈自身温升)

◆试验设备:

- 电感值:HP4284A, HP4285A 或同等仪器
- 电流:HP4284+42841A
- 直流电阻: Chroma 16502 或同等仪器

◆产品型号:

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	(D	

<u>7032</u>

(1)	412
	类型 Type
CTH.	闭磁路贴片电感
SMDRS	Shielded SMT Power Inductors

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J:±5%,K: ±10%, L: ±15% M: ±20%,P: ±25%, N: ±30%

公差 Inductance Tolerance

Features:

- High saturation current, low DCR
- Close magnetic circuit design reduce leakage
- Hig hlyaccurate dimensions for automatic mounting
- Various package size and wide inductance range
- RoHS, Halogen Free and REACH Compliance

Applications:

- Thin-screen TVs, LCDs, AV equipment, Gaming equipment
- Other electrical devices
- DC/DC converters, etc

Environmental Data:

Operating Temperature: -40°C to +125°C
 (Including coils self-temperature rise)

Test Equipment:

- L:HP4284A or HP4285A LCR meter or equivalent
- Isat & Irms: HP4284+42841A
- DCR:Chroma 16502 or equivalent

Product Identification:

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<u>M</u>

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外形尺寸(L:	×W×H) (mm)
External Dimer	nsions (L×W×H)
(m	nm)
104R	10.3×10.3×4.0

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Inductance

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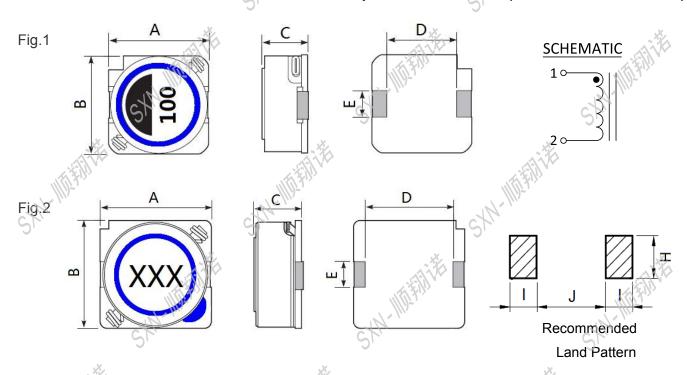
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	包装 Packing		
В	散装Bulk Package		
T	编带Tape & Reel		
W-III Fr		Ś	KN-IIII jan



◆外观尺寸:

Shape and Dimensions (dimensions are in mm):



Part No				ITE	M				
Skla	Shape	A G	В	С	D	SE	Н	I	J
SMDRS6028	Fig.1	6.0±0.2	6.0±0.2	2.8±0.2	3.0	2.0	2.2	2.0	3.0
SMDRS7028	Fig.1	7.0±0.2	7.0±0.2	2.8±0.2	4.0	2.0	2.2	2.0	4.0
SMDRS7030	Fig.1	7.0±0.2	7.0±0.2	3.0±0.2	4.0	2.0	2.2	2.0	4.0
SMDRS7032	Fig.1	7.0±0.2	7.0±0.2	3.2±0.2	4.0	2.0	2.2	2.0	4.0
SMDRS7045	Fig.1	7.0±0.2	7.0±0.2	4.5±0.3	4.0	2.0	2.2	2.0	4.0
SMDRS1045	Fig.2	10.1±0.2	10.1±0.2	4.5±0.3	6.0	3.2	3.2	2.5	5.6
SMDRS1255	Fig.2	12.5±0.3	12.5±0.3	5.5±0.35	8.6	3.2	3.2	2.5	8.6
SMDRS1265	Fig.2	12.5±0.3	12.5±0.3	6.5±0.35	8.6	3.2	3.2	2.5	8.6
SMDRS1275	Fig.2	12.5±0.3	12.5±0.3	7.5±0.35	8.6	3.2	3.2	2.5	8.6

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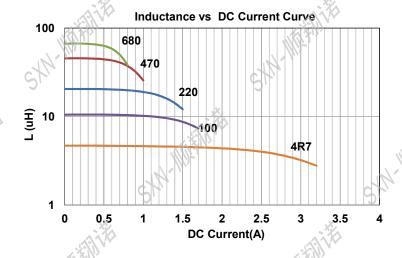
◆规格特性:

Specifications:

• SMDRS6028 Series Electrical Characteristics (Electrical specifications at 25℃)

Dord No.		nductance	•	DCR	Saturation Current	Temperature Rise Current
Part No	L(μH) '@0A	Tole	Test Freq	(Ω) Max	(A) Max	(A) Max
SMDRS6028-4R7N	4.7	N	100KHz	0.036	1.60	2.50
SMDRS6028-6R8N	6.8	N	100KHz	0.052	1.50	2.20
SMDRS6028-100M	10	M	100KHz	0.068	1.30	1.80
SMDRS6028-150M	15	M	100KHz	0.100	1.00	1.40
SMDRS6028-220M	22	М	100KHz	0.120	0.77	1.30
SMDRS6028-330M	33	М	100KHz	0.180	0.69	1.10
SMDRS6028-470M	47	М	100KHz	0.270	0.59	0.92
SMDRS6028-680M	68	М	100KHz	0.390	0.50	0.78

Saturation current



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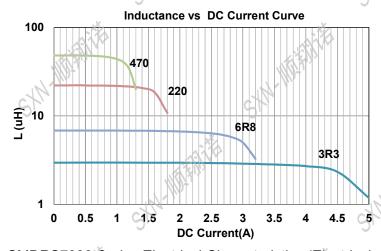
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• SMDRS7028 Series Electrical Characteristics (Electrical specifications at 25℃)

Part No	n jä	Inductance			Saturation Current	Temperature Rise Current
Part NO	L(μH) '@0A	Tole	Test Freq	(Ω) Max	(A) Max	(A) Max
SMDRS7028-3R3N	3.3	N	100KHz	0.037	1.60	1.60
SMDRS7028-4R7N	4.7	N	100KHz	0.045	1.50	1.50
SMDRS7028-6R8N	6.8	N	100KHz	0.59	1.30	1.30
SMDRS7028-100M	10	M	100KHz	0.083	1.10	1.10
SMDRS7028-150M	15	M	100KHz	0.130	0.88	0.88
SMDRS7028-220M	22	М	100KHz	0.180	0.75	0.75
SMDRS7028-330M	33	М	100KHz	0.240	0.65	0,65
SMDRS7028-470M	47	М	100KHz	0.340	0.54	0.54

Saturation current



• SMDRS7030 Series Electrical Characteristics (Electrical specifications at 25℃)

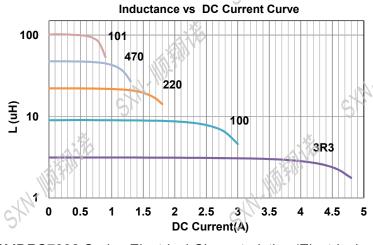
Part No	nductance		DCR	Saturation Current	Temperature Rise Current	
SPARTINO	L(µH)	Tole	Test	(Ω)	(A)	(A)
	'@0A		Freq	Max	Max	Max
SMDRS7030-3R3N	3.3	N	100KHz	0.023	1.80	1.80
SMDRS7030-4R7N	4.7	Ν	100KHz	0.036	1.60	1,60
SMDRS7030-6R8N	6.8	Ν	100KHz	0.041	1.50	1.50
SMDRS7030-100M	10	М	100KHz	0.053	1.30	1.30
SMDRS7030-150M	15	М	100KHz	0.084	1.00	1.00
SMDRS7030-220M	22	М	100KHz	0.110	0.86	0.86
SMDRS7030-330M	33	M	100KHz	0.160	0.65	0.65
SMDRS7030-470M	47	M	100KHz	0.240	0.57	0.57
SMDRS7030-680M	68	М	100KHz	0.310	0.49	0.49
SMDRS7030-101M	100	М	100KHz	0.450	0.35	0.35

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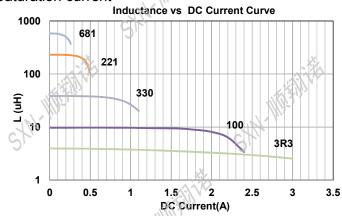
Saturation current



SMDRS7032 Series Electrical Characteristics (Electrical specifications at 25℃)

Part No		nductance)	DCR	Saturation Current	Temperature Rise Current	
	L(μH) '@0A	Tole	Test S Freq	(Ω) Max	(A) Max	(A) Max	
SMDRS7032-3R3N	3.3	N	100KHz	0.023	1.90	1.90	
SMDRS7032-4R7N	4.7	N (100KHz	0.036	1.70	1.70	
SMDRS7032-6R8N	6.8	NY	100KHz	0.041	1.60	1.60	
SMDRS7032-100M	10	M	100KHz	0.053	1.40	1.40	
SMDRS7032-150M	15 x	M	100KHz	0.075	1.10	1.10	
SMDRS7032-220M	22	M	100KHz	0.110	0.96	0.96	
SMDRS7032-330M	\33	M	100KHz	0.160	0.75	0.75	
SMDRS7032-470M	47	M	100KHz	0.240	0.67	0.67	
SMDRS7032-680M	68	M	100KHz 5	0.310	0.59	0.59	
SMDRS7032-101M	100	M	100KHz	0.450	0.45	0.45	
SMDRS7032-151M	150	М	100KHz	0.650	0.37	0.37	
SMDRS7032-221M	220	M W	100KHz	1.050	0.29	0.29	
SMDRS7032-331M	330	M	100KHz	1.670	0.22	0.22	
SMDRS7032-471M	470	M	100KHz	2.050	0.20	0.20	
SMDRS7032-681M	680	М	100KHz	3.150	0.16	0.16	
SMDRS7032-102M	1000	М	100KHz	4.780	0.13	0.13	

Saturation current

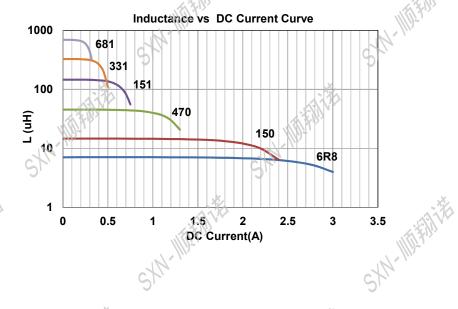




• SMDRS7045 Series Electrical Characteristics (Electrical specifications at 25℃)

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Dord No.		nductance	•	DCR	Saturation Current	Temperature Rise Current
Part No	L(µH) '@0A	Tole	Test Freq	(Ω) Max	(A) Max	(A) Max
SMDRS7045-4R7N	4.7	N	100KHz	0.200	2.50	2.30
SMDRS7045-6R8N	6.8	N	100KHz	0.030	2.00	2.10
SMDRS7045-100M	10	М	100KHz	0.039	1.70	1.74
SMDRS7045-150M	15	M	100KHz	0.036	1.30	1.78
SMDRS7045-220M	22	M	100KHz	0.052	1.10	1.53
SMDRS7045-330M	33	М	100KHz	0.061	0.90	1.34
SMDRS7045-470M	47	М	100KHz	0.096	0.82	1.09
SMDRS7045-680M	68	М	100KHz	0.125	0.75	0.92
SMDRS7045-101M	100	М	100KHz	0.175	0.60	0.77
SMDRS7045-151M	150	М	100KHz	0.250	0.50	0.65
SMDRS7045-221M	220	М	100KHz	0.340	0.40	0.55
SMDRS7045-331M	330	М	100KHz	0.520	0.33	0.45
SMDRS7045-471M	470	M	100KHz	0.740	0.25	0.37
SMDRS7045-681M	680	M	100KHz	1.050	0.22	0.31
SMDRS7045-102M	1000	М	100KHz	1.480	0.20	0.27

Saturation current



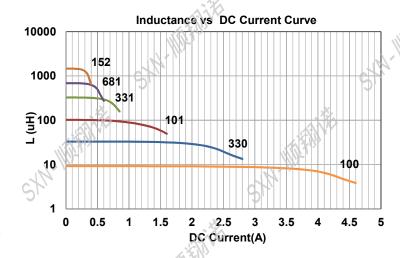
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• SMDRS1045 Series Electrical Characteristics (Electrical specifications at 25℃)

D. AN.	li AŽ	nductance	•	DCR	Saturation Current	Temperature Rise Current	
Part No	L(µH) '@0A	Tole	Test Freq	(Ω) Max	(A) Max	(A) Max	
SMDRS1045-100M	10	М	100KHz	0.036	3.00	2.50	
SMDRS1045-150M	15	M	100KHz	0.047	2.40	2.20	
SMDRS1045-220M	22	М	100KHz	0.059	2.10	1.90	
SMDRS1045-330M	33	M W	100KHz	0.082	1.60	1.70	
SMDRS1045-470M	47	M	100KHz	0.100	1.40	1.50	
SMDRS1045-680M	68	M	100KHz	0.140	1.20	1.30	
SMDRS1045-101M	100	M	100KHz	0.200	1.00	1.10	
SMDRS1045-151M	150	M	100KHz	0.350	0.79	0.81	
SMDRS1045-221M	220	M	100KHz	0.470	0.65	0.70	
SMDRS1045-331M	330	M	100KHz	0.680	0.54	0.58	
SMDRS1045-471M	470	M	100KHz	1.030	0.47	0.47	
SMDRS1045-681M	680	M	100KHz	1.600	0.38	0.38	
SMDRS1045-102M	1000	M	100KHz	2.800	0.32	0.29	
SMDRS1045-152M	1500	M	100KHz	2.400	0.22	0.26	
• Saturation current 10000 152 1000 681	nductance vs. D	OC Current C	urve	N-III Filit		SXN-IIII Filit	

Saturation current



http://www.sxndz.com

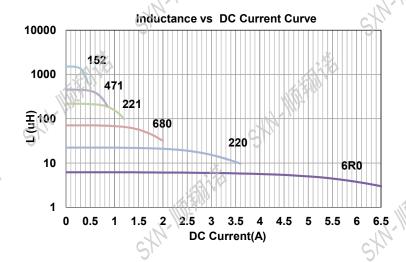
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• SMDRS1255 Series Electrical Characteristics (Electrical specifications at 25℃)

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	Part No		nductance)	DCR	Saturation Current	Temperature Rise Current	•		
	Part No	L(µH)	Tole	Test	(Ω)	(A)	(A)			
		/_'@0A		Freq	Max	Max	Max			
	SMDRS1255-6R0N	6.0	N	100KHz	0.016	3.60	4.90			
	SMDRS1255-100M	10	М	100KHz	0.021	3.40	4.30			
	SMDRS1255-150M	15	М	100KHz	0.025	2.80	3.90			
	SMDRS1255-220M	22	M	100KHz	0.033	2.30	3.40			
	SMDRS1255-330M	33	M	100KHz	0.041	1.90	3.10			
	SMDRS1255-470M	47	М	100KHz	0.061	1.60	2.50			
V- _	SMDRS1255-680M	68	М	100KHz	0.083	1.30	2.20			
	SMDRS1255-101M	100	М	100KHz	0.117	1.10	1.80			
	SMDRS1255-151M	150	М	100KHz	0.190	0.88	1.40			
	SMDRS1255-221M	220	М	100KHz	0.270	0.72	1.20			
_	SMDRS1255-331M	330	М	100KHz	0.410	0.59	1.00			
	SMDRS1255-471M	470	М	100KHz	0.520	0.49	0.88			
	SMDRS1255-681M	380	M	100KHz	0.760	0.43	0.73	(
_ 	SMDRS1255-102M	1000	M	100KHz	1.120	0.34	0.60			
	SMDRS1255-152M	1500	М	100KHz	1.730	0.29	0.48			

Saturation current



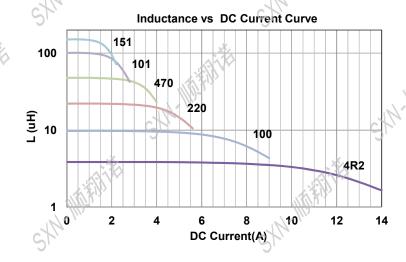
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• SMDRS1265 Series Electrical Characteristics (Electrical specifications at 25℃)

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Dovt No.		lı Ağı	nductanc	e	DCR	Saturation Current	Temperature Rise Current		
	Part No	L(µH) '@0A	Tole	Test Freq	(Ω) Max	(A) Max	(A) Max		
	SMDRS1265-2R0N	2.0	N	100KHz	0.011	10.00	6.20		
-	SMDRS1265-4R2N	4.2	N	100KHz	0.015	7.30	5.50		
	SMDRS1265-7R0N	7.0	N	100KHz	0.017	5,70	5.00		
-	SMDRS1265-100M	10	M	100KHz	0.020	5.00	4.80		
-	SMDRS1265-150M	15	CM	100KHz	0.023	4.20	4.40		
_	SMDRS1265-220M	22	М	100KHz	0.031	3.50	3.80		
γ -	SMDRS1265-330M	33	М	100KHz	0.040	2.80	3.40		
_	SMDRS1265-470M	47	М	100KHz	0.057	2.40	2.80		
-	SMDRS1265-680M	68	М	100KHzC	0.078	2.00	2.40		
-	SMDRS1265-101M	100	М	100KHz	0.123	1.60	1.90		
	SMDRS1265-151M	150	М	100KHz	0.273	1.00	1.20		
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Saturation current



http://www.sxndz.com

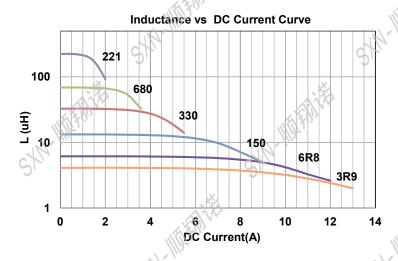
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• SMDRS1275 Series Electrical Characteristics (Electrical specifications at 25℃)

Dord No.	11 THE	nductance)	DCR	Saturation Current	Temperature Rise Current
Part No	L(µH) '@0A	Tole	Test Freq	(Ω) Max	(A) Max	(A) Max
SMDRS1275-1R2N	1.2	N	100KHz	0.006	13.00	8.20
SMDRS1275-2R7N	2.7	N	100KHz	0.009	10.00	7.00
SMDRS1275-3R9N	3.9	N	100KHz	0.010	9.00	6.70
SMDRS1275-5R6N	5.6	M	100KHz	0.011	7.80	6.30
SMDRS1275-6R8N	6.8	CM	100KHz	0.013	7.20	5.90
SMDRS1275-100N	10	М	100KHz	0.015	5.50	5.40
SMDRS1275-152N	15	М	100KHz	0.018	4.70	5.00
SMDRS1275-220N	22	М	100KHz	0.026	4.00	4.00
SMDRS1275-330N	33	М	100KHz	0.039	3.20	3.40
SMDRS1275-470N	47	М	100KHz	0.052	2.70	3.00
SMDRS1275-680N	68	М	100KHz	0.077	2.00	2.40
SMDRS1275-101N	100	M	100KHz	0.125	1.90	1.90
SMDRS1275-151N	150	MI	100KHz	0.175	1.50	1.60
SMDRS1275-221M	220	M	100KHz	0.258	1.30	1.30

Saturation current

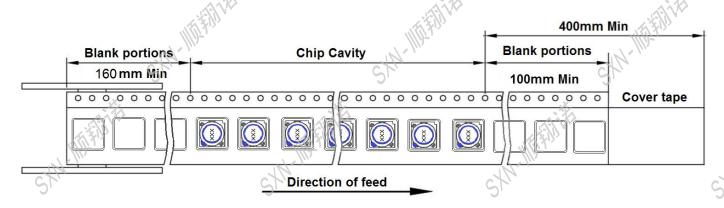


- •Saturation Current: DC current at which inductance drops 10%(0628 is 30%) from its value without current.
- ●Temperature Rise Current: the actual value of DC current when the temperature rise isΔT 40 °C (Ta=25 °C).
- Rated DC Current: The less value which is Isat or Irms.
- Special remind: Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

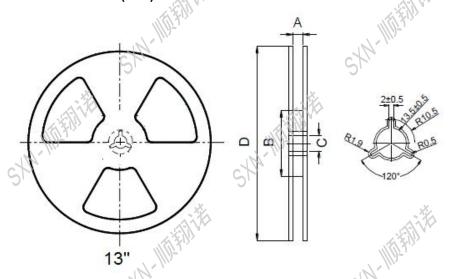


◆产品包装: Packaging:

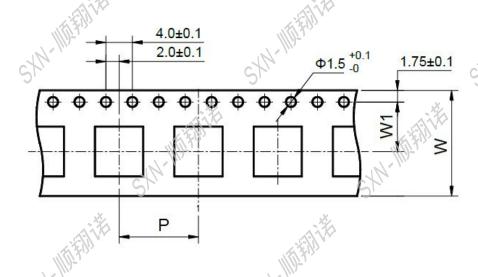
• Tape and Reel Specifications: (Dimensions are in mm)



Reel Dimensions (mm)

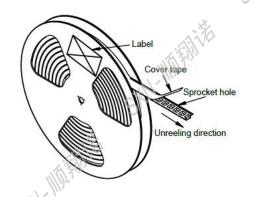


●Tape Dimension (mm)

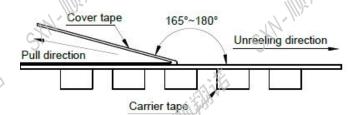




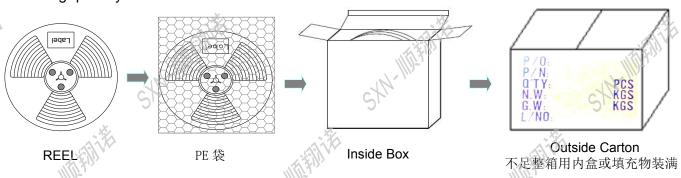
• Cover tape peel off condition



- a) Cover tape peel force shall be 10 to 120g
- b) Noodle strip peeling angle165° to 180°



Packing quantity



Part No.	Tape Dimension		Reel Dimensions			REEL	Inside	Outside		
Part No.	W	P	W1	Α	В	С		(PCS)	Box(PCS)	Carton(PCS)
SMDRS6028	16	12	7.5	16.4	60	13	330	2000	6000	24,000
SMDRS7028	16	12	7.5	16.4	60	13	330	1000	3000 5	12,000
SMDRS7030	16	12	7.5	16.4	60	13	330	1000	3000	12,000
SMDRS7032	16	12	7.5	16.4	60	13	330	1000	3000	12,000
SMDRS7045	16	12	7.5	16.4	60	13	330	1000	3000	12,000
SMDRS1045	24	16	11.5	24.4	60	13	330	500	1000	4000
SMDRS1255	24	16	11.5	24.4	60	13	330	500	1000	4000
SMDRS1265	24	16	11.5	24.4	60	13	330	500	1000	4000
SMDRS1275	24	16	11.5	24.4	60	13	330	500	1000	4000

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◆可靠性测试: Reliability Testing:

▼ 月 筆 注 例 风:	51	Kellability lesting:
Items	Requirements	Test Methods and Remarks
Terminal Strength Reference docu ments: GB/T 2423.60-2008 端子強度(SMT)	1. Pulling test: Define: A: sectional area of terminal A≤8mm2 force≥5N time:30sec 8mm2 <a≤20mm2 10sec="" 2.solder="" 20mm2<a="" 3.meet="" above="" any="" force≥10n="" force≥20n="" loose="" paste="" requirements="" td="" terminal<="" the="" thickness:0.12mm="" time:="" without=""><td>Solder the inductor to the testing jig using leadfree solder. Then apply a force in the Keep time: 10±1s Speed: 1.0mm/s.</td></a≤20mm2>	Solder the inductor to the testing jig using leadfree solder. Then apply a force in the Keep time: 10±1s Speed: 1.0mm/s.
erminal Strength Reference docu ments: GB/T 2423.60-2008 端子強度(DIP)		Pull Force:the force shall be applied gradually to the terminal and thenmaintained for 10 seconds. Pulling test
Resistance to Flexure	1.No visible mechanical damage.	1.Solder the inductor to the test jig (glass epoxy board 2.shown in Using a leadfree solder. Then apply a force in the direction shown 3.Flexure: 2mm.
JIS C 5321:1997 抗弯曲性试验	SM-IIII FAITH	4.Pressurizing Speed: 0.5mm/sec. 5.Keep time: 30 sec. R230 R230 Flexure
Dropping Reference documents: GB/T 2423.7-2018 落下試驗	1.No case deformation or change inappearance. 2.No short and no open.	1.Drop the packaged products from 1m high in 1 angle, 3 ridges and 6surfaces, twice in each direction.
Solderability Reference documents: GB/T 2423.28-2005 可焊性试验	3.Terminals must have 95% minimum solder	1.Solder temperture:240 ± 2°C 2.Duration: 3 sec. 3. Solder: Sn/3 0Ag/0.5Cu. 4.Flux: 25% Resin and 75% ethanol in weight



	Sr.	<u> </u>			
Items	Requirements	Test Methods and Remarks			
	1.No visible mechanical damage.	1. Solder the inductor to the testing jig (glass epoxy			
	2. Inductance change: Within ±10%.	boardshown in) using leadfree solder.			
	3 Q factor change: Within ±20%.	2.The inductor shall be subjected to a simple			
	D) Solder and	harmonic motion having total amplitude of 1.5mm,			
	Cu pad Solder mask	the frequency being varieduniformly between the			
		approximate limits of 10 and 55 Hz.			
Vibration		3.The frequency range from 10 to 55 Hz and			
Reference documents:		return to 10 Hz shallbe traversed in approximately			
GB/T 2423.10-2019	Glass Epoxy Board	1 minute. This motion shall be applied for a period			
振動試验		of 2 hours in each 3mutually perpendicular			
		directions(total of 6 hours).			
	(1)-111/2°	Freq			
	SKI,	55Hz			
Х.	Sr.				
		10Hz			
		0 1Min Time			
CHA	1.No visible mechanical damage.	1.Start at (85~125℃) for T time, rush to i: (-55~40℃) for T time as one cycle, go through100 cycles.			
	2. Inductance change: Within ±10%.(Mn-Zn:				
	Within $\leq 30\%$)				
Thermal Shock	3.Q factor change: Within ±20%.	2.Transforming interval: Max. 20 sec.			
Reference documents:	d'Ille	3.Tested cycle: 100 cycles.			
GB/T 2423.22-2012	St. St.	4. The chip shall be stabilized at normal condition			
Method Na	38.	for 1~2 hours			
冷热冲击试验		125°C/85°C 30 min. 30 min.			
14 W/11 III MAN	W. J. I.	Ambient Ambient			
CAN. II.	M. III	Temperature 30 min.			
51	Si	20sec. (max.)			
	1.No visible mechanical damage.	1.Temperature:M(-55~-40±2°C)			
	2. Inductance change: Within ±10%.(Mn-Zn:	2. Duration: 96±2 hours			
Low temperature Storage	Within ≤ 30%)	3. The chip shall be stabilized at normal condition for			
Reference documents:	3.Q factor change: Within ±20%.	1~2 hoursbefore measuring.			
GB/T 2423.1-2008		Room			
Method Ab		Temp 96H Test			
低温储存试验	M-III	97H 98H Time			
Sr	Sr'	M°C Low temperature			
	·%	Temp			

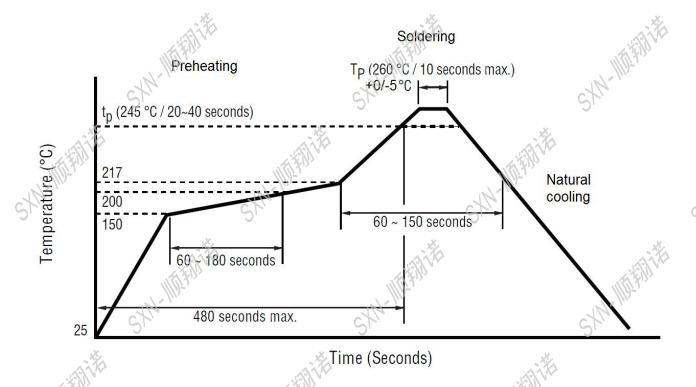


_	GT'	C N
Items	Requirements	Test Methods and Remarks
	1.No visible mechanical damage.	1.Temperature:N(125~85±2℃).
High temperature	2. Inductance change: Within ±10%.(Mn-Zn:	2.Duration: 96±2 hours
Storage	Within ≦30%)	3.The chip shall be stabilized at normal condition
	3.Q factor change: Within ±20%.	for 1~2 hoursbefore measuring.
GB/T 2423.2-2008	**	Temp High temperature
Method Bb		N'C
高温储存试验	11/2/2	Room
SH	Str	0 Test 96H 97H 98H Time
	1.No visible mechanical damage.	1.Temperature: 60±2℃
Ì	2. Inductance change: Within ±10%.(Mn-Zn:	2.Humidity: 90% to 95% RH.
Damp Heat	Within ≦30%)	3.Duration: 96±2 hours.
(Steady States)	3.Q factor change: Within ±20%.	4.The chip shall be stabilized at normal condition
Reference documents:	Dr. St.	for 1~2 hoursbefore measuring.
GB/T 2423.3-2016	, N.	Temp & Humidity 60°C Temp & Humidity 60°C
恒定湿热试验	14 JVC	93%RH High temperature High humidity
	11/1/2/2	Conditions
cth	c the	0 96H 97H 98H Time
Heat endurance of	1.No significant defects in appearance.	1.Refer to the above reflow curve and go through
Reflow soldering	2. △ L/L ≦ 10% (Mn-Zn: △ L/L ≦ 30%)	the reflow for twice.
Reference documents:	3. ∆ Q/Q≦30% (SMD series only)	2.The peak temperature : 260+0/-5℃
GJB 360B-2009	4. △ DCR/DCR ≦ 10%	
回流焊耐热性试验	14 24	£20
	No case deformation or change in	To dip parts into IPA solvent for 5±0.5Min,then
Resistance to solvent	appearance or obliteration of marking	drying them at room temp for 5Min,at last ,to
test		brushing making 10 times.
Reference documents:	W - Mar	10 m
IEC 68-2-45:1993 耐溶剂性试验	SX	SKI
	JX.	
Overload test	1.During the test no smoke, no peculiar,	
	smell, no fire	
JIS C5311-6.13	2.The characteristic is normal after test	Apply twice as rated current for 5 minutes.
过负荷试验	br Sr	SN
voltage resistance test	1.During the test no breakdown	
\ \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	Z.The characteristic is normal after test	
MIL-STD-202G Method	17-1113-	1. For parts with two coils
301	SK	2. DC1000V, Current: 1mA, Time: 1Min.
绝缘耐压测试	JC.	Refer to catalogue of specific products
A		



◆推荐回流焊温度曲线

Recommended reflow soldering curve:



The recommended reflow conditions as above graph, is set according to our soldering equipment. DUE to various manufactures may have different reflow soldering equipment, products, process conditions, set methods. And so on, when setting the reflow conditions, Please adjust and confirm according to users' environment/equipment.

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使用注意事项

REMINDERS FOR USING THESE PRODUCTS



● 保存时间为12 个月以内,保存条件(温度5~40°C以下、湿度35 ~ 66%RH 以下),需充分注意。 若超过保存时间,端子电极的可焊性将可能老化。

The storage period is within 12 months. Be sure to follow the storage conditions (temperature: $5\sim40^{\circ}$ C, humidity: 35 to 65% RH or less). If the storage period elapses, the soldering of the terminal electrodes may deteriorate.

• 请勿在气体腐蚀环境(盐、酸、碱等)下使用和保存。

Do not use or store in locations where there are conditions such as gas corrosion (salt, acid, alkali, etc.).

• 手上的油脂会导致可焊性降低,应避免用手直接接触端子。

Don't touch electrodes directly with bare hands as oil secretions may inhibit soldering Always ensure optimum conditions for soldering.

请小心轻拿轻放,避免由于产品的跌落或取出不当而导致的损坏。

Please always handle products carefully to prevent any damage caused bydropping down or inappropriate removing.

• 端子过度弯曲会导致断线,请不要过度弯曲端子。

Don't bend the terminals with excessive stress in case of any wire fracture.

• 不要清洗产品, 如需要清洗时请联系我司。

Don't rinse coils by yourself and please contact SXN if necessary.

• 请勿将本产品靠近磁铁或带有磁力的物体

Don't expose the products to magnets or magnetic fields

- 在实施焊接前,请务必进行预热。预热温度与焊接温度及芯片温度的温度差要在150°C 以内。
 Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- 安装后的焊接修正应在规格书规定的条件范围内。若加热过度可能导致短路、性能降低、寿命减少。
 Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- 装置会因通电而自我发热(温度上升),因此在热设计方面需留有充分余地。
 Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- 非磁屏蔽型在基板设计时需注意配置线圈,受到电磁干扰可能会导致误动作。
 Carefully lay out the coil for the circuit board design of the non-magnetic shield type. A malfunction may occur due to magnetic interference.
- 当本公司产品使用在一般电子设备以外的场合,如:车载,医疗设备,军用,航空航天等,请务必联繫本公司营业部门, 如超出本公司产品使用条件而引起的机器故障时,本公司概不负责。
 - If SXN product will be applied in area like automotive product, medical equipment, military and aerospace except generalelectronic device, please keep SXN sales informed in advance. SXN shall not be held liable for any malfunction or breakdowncaused by using product in the condition which is inconsistent with that recommended by SXN.